Ultrasonic Distance Sensor

Project Title: Designed for: Public Release

Assembly Variant: 001

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Revision History

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<td>N/A</td>
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</tbody>
</table>

Version control disabled

SVN Rev: TIDA-01386

Number: Rev: E1

TID #: TIDA-01386

Orderable: N/A

Block Diagram

Sheet Title: Size: Mod. Date: File:

http://www.ti.com

Contact: http://www.ti.com/support

LM5166

TVS3300

8V

PGA460

MSP430FR5959

IO-Link Stack

TIOL111

IO-Link

3.3V LDO

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